SN54F11, SN74F11 TRIPLE 3-INPUT POSITIVE-AND GATES

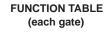
SDFS040A - MARCH 1987 - REVISED OCTOBER 1993

 Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

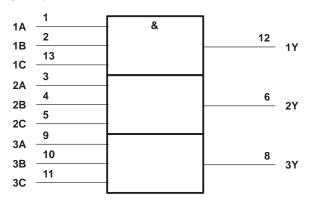
These devices contain three independent 3-input AND gates. They perform the Boolean functions $Y = A \cdot B \cdot C$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

The SN54F11 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F11 is characterized for operation from 0°C to 70°C.



	INPUTS	OUTPUT	
Α	В	Y	
Н	Н	Н	Н
L	Х	Х	L
Х	L	Х	L
Х	Х	L	L

logic symbol[†]

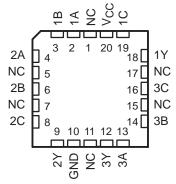


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

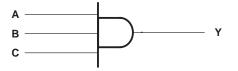
SN54F11 J PACKAGE SN74F11 D OR N PACKAGE (TOP VIEW)										
4		∇	-							
1A L	1	14	V _{CC}							
1B 🛛	2	13] V _{CC}] 1C							
2A [3	12] 1Y							
2B 🛛	4	11	3C							
2C 🛛	5	10	3B							
2Y [GND [6	9	3A							
GND [7	8] 3Y							

SN54F11 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram, each gate (positive logic)





SN54F11, SN74F11 TRIPLE 3-INPUT POSITIVE-AND GATES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high state	$\dots -0.5$ V to V _{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range: SN54F11	–55°C to 125°C
SN74F11	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

			SN54F11		5	SN74F11		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
Iк	Input clamp current			-18			-18	mA
ЮН	High-level output current			– 1			– 1	mA
IOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TE			SN54F11		ŝ			
PARAMETER	TEST CONDITIONS			TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = – 18 mA			-1.2			-1.2	V
Maria	V _{CC} = 4.5 V,	I _{OH} = – 1 mA	2.5	3.4		2.5	3.4		V
VOH	V _{CC} = 4.75 V,	I _{OH} = – 1 mA				2.7			V
V _{OL}	V _{CC} = 4.5 V,	I _{OL} = 20 mA		0.3	0.5		0.3	0.5	V
lj	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
IН	V _{CC} = 5.5 V,	VI = 2.7 V			20			20	μΑ
١ _{١L}	V _{CC} = 5.5 V,	VI = 0.5 V			- 0.6			- 0.6	mA
IOS§	V _{CC} = 5.5 V,	$V_{O} = 0$	-60		-150	-60		-150	mA
Іссн	V _{CC} = 5.5 V,	V _I = 4.5 V		4.1	6.2		4.1	6.2	mA
ICCL	V _{CC} = 5.5 V,	$V_{I} = 0$		6.5	9.7		6.5	9.7	mA

[‡] All typical values are at V_{CC} = 5 V, $T_A = 25^{\circ}C$.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.



SN54F11, SN74F11 TRIPLE 3-INPUT POSITIVE-AND GATES

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switching characteristics

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CI RI	CC = 5 V _ = 50 pl _ = 500 s _ = 25°C _ /F11 	F, Ω,	CL RL	= 50 pF = 500 Ω = MIN t			UNIT
^t PLH	A B or C	V	2.2	3.8	5.6	1.7	7.5	2.2	6.6	
^t PHL	A, B, or C	Ť	1.7	3.7	5.5	1.2	7.5	1.7	6.5	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.





PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9758101Q2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9758101Q2A SNJ54F 11FK
5962-9758101QCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9758101QC A SNJ54F11J
5962-9758101QDA	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9758101QD A SNJ54F11W
JM38510/34002B2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002B2A
JM38510/34002B2A.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002B2A
JM38510/34002BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002BCA
JM38510/34002BCA.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002BCA
JM38510/34002BDA	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002BDA
JM38510/34002BDA.A	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002BDA
M38510/34002B2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002B2A
M38510/34002BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002BCA
M38510/34002BDA	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 34002BDA
SN54F11J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54F11J
SN54F11J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54F11J
SN74F11D	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	0 to 70	F11
SN74F11D.B	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	0 to 70	F11
SN74F11DR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F11



22-Aug-2025

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74F11DR.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F11
SN74F11DR.B	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F11
SN74F11N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F11N
SN74F11N.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F11N
SN74F11NSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F11
SN74F11NSR.A	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F11
SNJ54F11FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9758101Q2A SNJ54F 11FK
SNJ54F11FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9758101Q2A SNJ54F 11FK
SNJ54F11J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9758101QC A SNJ54F11J
SNJ54F11J.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9758101QC A SNJ54F11J
SNJ54F11W	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9758101QD A SNJ54F11W
SNJ54F11W.A	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9758101QD A SNJ54F11W

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.



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PACKAGE OPTION ADDENDUM

22-Aug-2025

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54F11, SN74F11 :

Catalog : SN74F11

Military : SN54F11

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications



Texas

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions are nominal												
	Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74F11DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74F11NSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

Pack Materials-Page 1



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PACKAGE MATERIALS INFORMATION

23-Jul-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F11DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74F11NSR	SOP	NS	14	2000	353.0	353.0	32.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal	
-----------------------------	--

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-9758101Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9758101QDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/34002B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/34002B2A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/34002BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/34002BDA.A	W	CFP	14	25	506.98	26.16	6220	NA
M38510/34002B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/34002BDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74F11N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F11N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F11N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74F11N.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54F11FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54F11FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54F11W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54F11W.A	W	CFP	14	25	506.98	26.16	6220	NA

D0014A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



D0014A

EXAMPLE BOARD LAYOUT

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



D0014A

EXAMPLE STENCIL DESIGN

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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